

possible to manufacture the laminated composite electronic device by baking without deformation nor cracks forming therein.

Yamaguchi discloses a second ceramic portion [7, 7'] including a magnetic material having magnetic powder uniformly dispersed therein. The material included in the second ceramic portion [7, 7'] (magnetic material) is different from a material included in a first ceramic portion [1, 1'] (dielectric material).

In contrast, as recited in claim 9 of the present invention, a second ceramic portion includes one or more second layers including the same first material as in the first ceramic portion and discrete portions distributed on a surface thereof including a second material different from the first material. Thus, the present invention differs from Yamaguchi in construction.

Further, the present invention is advantageous in that the above construction permits the first ceramic portion to be joined to the second ceramic portion without any problems of deflection, separation, and cracking. In Yamaguchi, on the other hand, in order to prevent deformation such as warpage and cracking when the first ceramic portion [1, 1'] is joined to the second ceramic portion [7, 7'], intermediate layers a-d having thermal expansion rates differing from each other need to be inserted therebetween. Accordingly, Yamaguchi does not provide the advantage of the present invention.

Yamaguchi also fails to disclose a green sheet for forming the second ceramic portion recited in claim 13 of the present invention, that is, a green sheet including a layer including a

first material and discrete portions distributed on a surface thereof including a second material different from the first material.

Thus, the 35 USC §102(e) rejection should be reconsidered and withdrawn.

Claim 11 stands rejected under 35 USC §103(a) as unpatentable over Yamaguchi in view of U.S. Patent 5,903,968 to Shouji (hereinafter "Shouji").

Applicants respectfully request reconsideration and withdrawal of this rejection.

Shouji discloses a method for manufacturing a magnetic head assembly, which is a completely different field of endeavor than that of the present invention. Fig. 2A of Shouji shows thin film magnetic transducers 22 formed on a wafer 21. The wafer 21 is finally cut into separate magnetic heads as shown in Fig. 2F. Thus, Shouji fails to show a layer including a first material and discrete portions distributed on a surface thereof including a second material different from the first material, as recited in claim 13 of the instant application.

Thus, the 35 USC §103(a) rejection should be reconsidered and withdrawn.

In view of the aforementioned remarks, claims 9-13 are in condition for allowance, which action, at an early date, is requested.

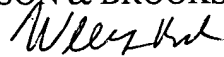
If, for any reason, it is felt that this application is not now in condition for allowance, the Examiner is requested to contact Applicants' undersigned attorney at the telephone number indicated below to arrange for an interview to expedite the disposition of this case.

U.S. Patent Application Serial No. 10/073,117
Response to Office Action dated November 30, 2004

In the event that this paper is not timely filed, Applicants respectfully petition for an appropriate extension of time. Please charge any fees for such an extension of time and any other fees which may be due with respect to this paper, to Deposit Account No. 01-2340.

Respectfully submitted,

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Enclosures: Petition for Extension of Time

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